

PROCESS FOR WAVE SOLDERING COMPONENTS ON A
PRINTED CIRCUIT BOARD IN A TEMPERATURE
CONTROLLED NON-OXIDIZING ATMOSPHERE

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Abstract of the Disclosure

10 The present invention relates to a wave soldering
process wherein an inert gas atmosphere is injected inside
the wave soldering machine, said inert gas atmosphere
having a temperature which might be controlled. Particu-
larly, the atmosphere can be heated at the same or
different temperatures before injection, for example in the
15 preheating zones, in the machine. The atmosphere can also
be cooled (or injected at ambient temperature) e.g. in the
cooling zone. Various atmospheres can be used (similar or
different from one zone to another). The thermal
efficiency of the heat transfer between the atmosphere and
20 the printed circuit boards is thus greatly enhanced, which
means less solder defects, higher components density and
decrease of energy consumption and inert gas flow rate.